

Lead-free solder paste

◆ Product Description

Environmentally friendly lead-free solder paste, in line with RoHS standards, high solder strength, bright and full solder joints, good fluidity and wettability, suitable for precision electronic manufacturing.



◆ Product Advantages

- Environmentally-friendly
- Lead-free
- RoHS compliant
- High soldering strength
- Good wettability

◆ Product Structure

Sn-Ag-Cu alloy is used as a base material, environment-friendly flux is added, uniform paste is prepared by mixing and grinding, and that paste is sealed and vacuum packaged without heavy metal pollution.

◆ Technical Features

Alloy composition:
 Sn96.5-Ag3.0-Cu0.5;
 Melting point: 217-221 ° C;
 Viscosity: 10000-15000 CPS;
 soldering temperature: 240-270 ° C;
 Shelf life: 3 months (refrigerated)

Item#	Weight	Packing
1.5.19.03.0004	0.6kg	Individually wrapped

◆ Application Scenarios

Precision electronic components welding, smart phone/computer manufacturing, automotive electronics production, environmental protection electronic equipment assembly, medical electronics processing

◆ Remarks

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